



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Features

- High impedance value
- Current rating up to 400 mA
- RoHS compliant*

Applications

- Noise suppression
- Personal computers
- Display panels

SRF3216 Series - Common Mode Chip Inductors

Electrical Specifications

Bourns Part No.	Impedance @ 100 MHz		Rated Voltage (DC)	Withstanding Voltage (DC)	Insulation Resistance (MΩ)	DCR Max. (Ω)	IDC Max. (mA)
	(Ω)	Tolerance (%)					
SRF3216-900Y	90	±25	50	125	10	0.30	400
SRF3216-161Y	160	±25	50	125	10	0.35	350
SRF3216-221Y	220	±25	50	125	10	0.45	300
SRF3216-261Y	260	±25	50	125	10	0.45	300
SRF3216-601Y	600	±25	50	125	10	0.80	300
SRF3216-102Y	1000	±25	50	125	10	1.00	230
SRF3216-222Y	2200	±25	50	125	10	1.20	200

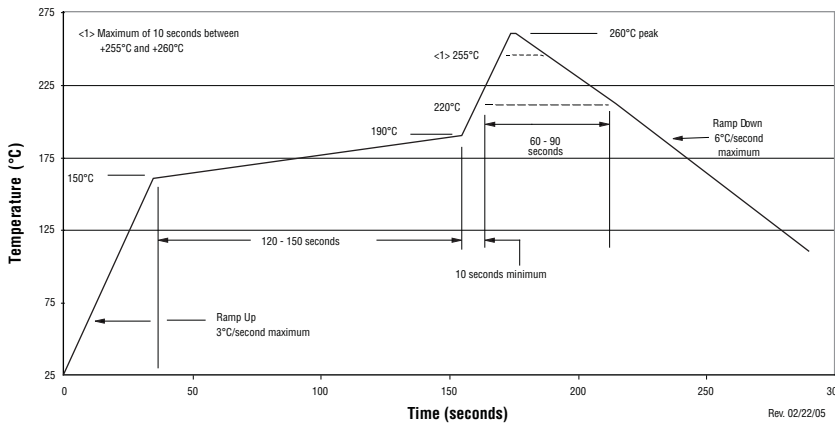
General Specifications

Reflow soldering 230 °C; 50 sec max.
 Operating Temperature
-55 °C to +125 °C
 (Temperature rise included)
 Storage Temperature
-55 °C to +125 °C
 Resistance to Soldering Heat
 260 °C, 10 sec. max.

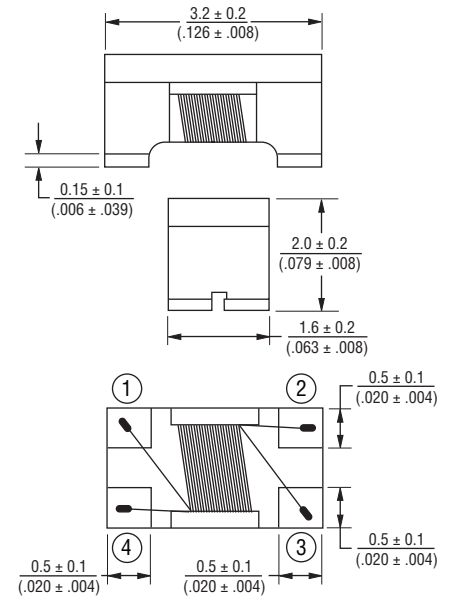
Materials

Core Ferrite
 Wire Enameled copper
 Terminal Ag/Ni/Sn
 Packaging 2000 pcs. per reel

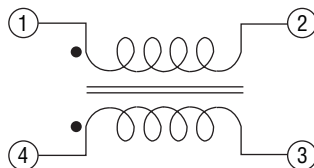
Soldering Profile



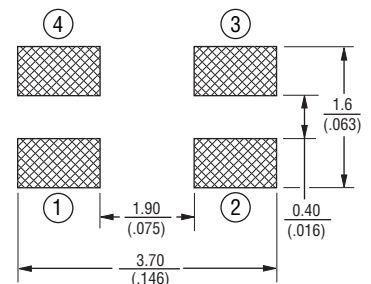
Product Dimensions



Schematic



Recommended Layout



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

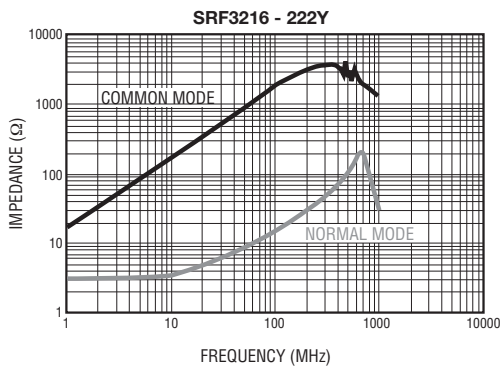
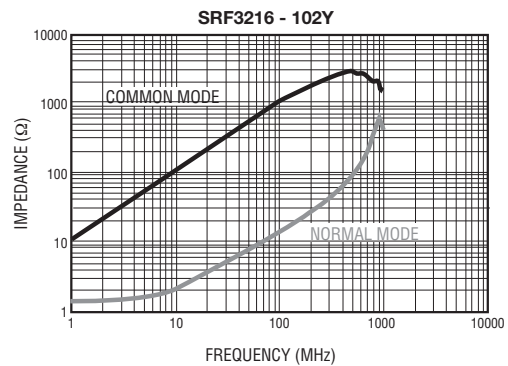
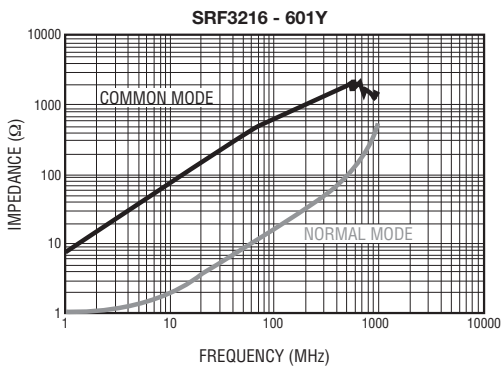
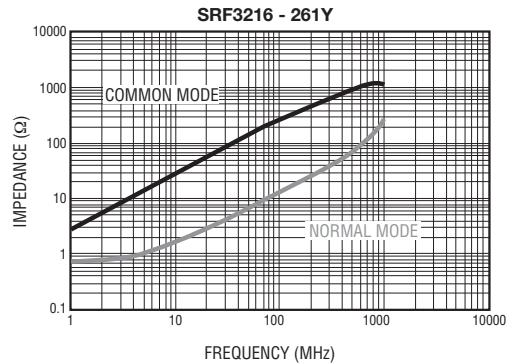
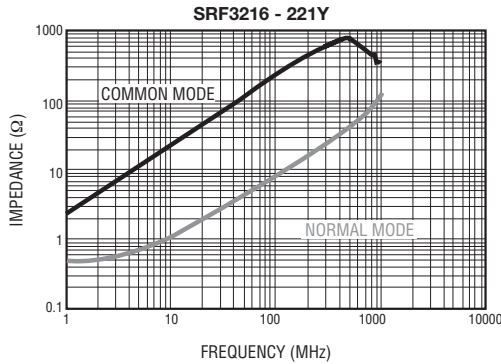
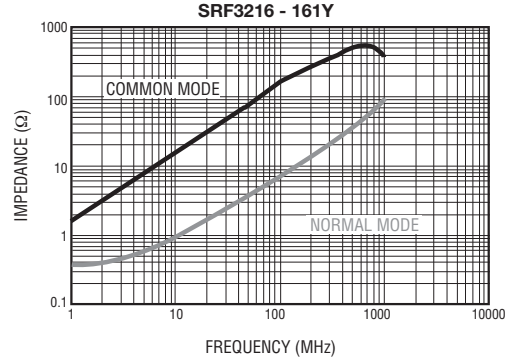
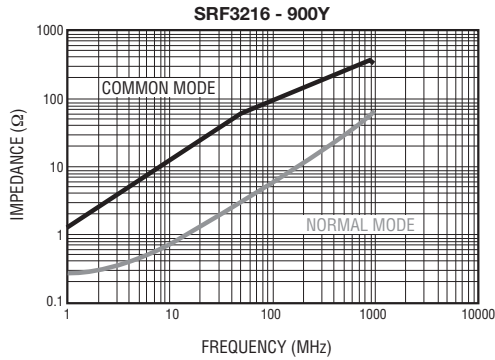
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.

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Impedance vs. Frequency

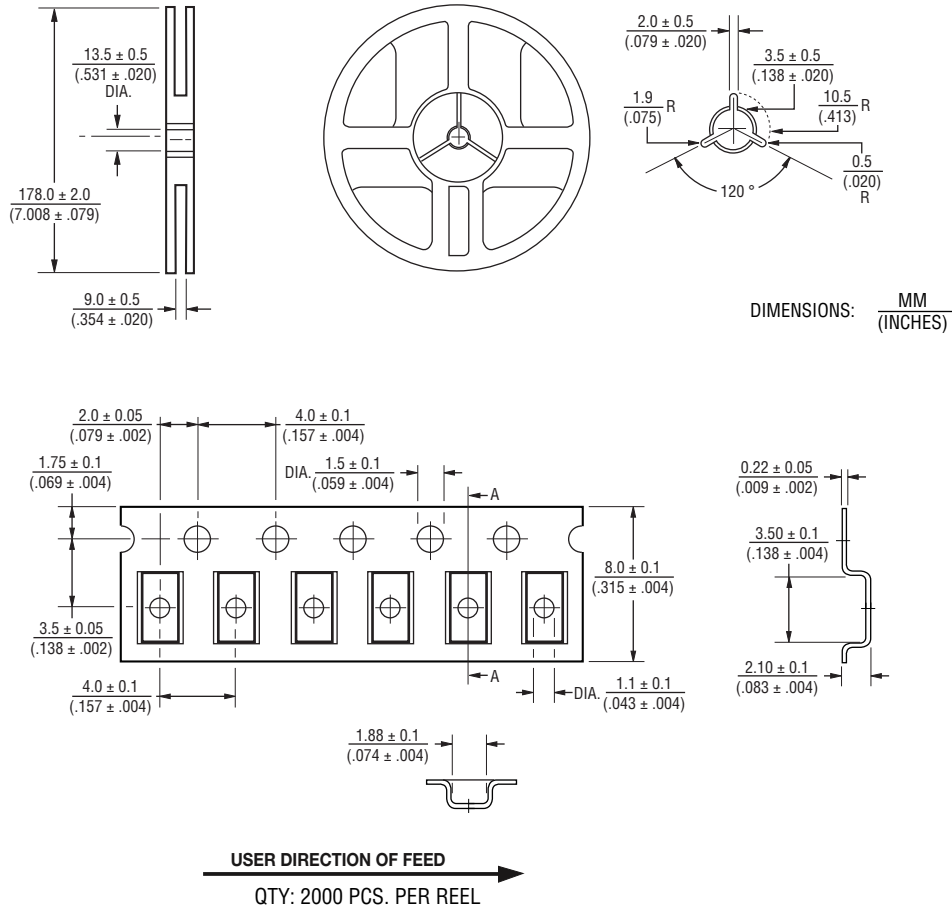


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Packaging Specifications



REV. 03/13

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